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Jung-Chih Chiao

Xuyuan Chen

Zhaoying Zhou

Xinxin Li

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Introduction

This conference, MEMS/MOEMS Technologies and Applications, is part of SPIE Photonics Asia, held at the Jiahua Grand Convention and Exhibition Center in Beijing, China, on 11–15 November 2007.

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**J.-C. Chiao
Xuyuan Chen
Xinxin Li
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